

SOT1318-1

plastic, thermal enhanced extremely thin quad flat package;
no leads; 32 terminals; 0.4 mm pitch; 4 mm x 4 mm x 0.5 mm
body

19 October 2017

Package information

1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	HXQFN32
Package type industry code	HXQFN32
Package style descriptive code	HXQFN (thermal enhanced extremely thin quad flatpack; no leads)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	30-11-2011
Manufacturer package code	SOT1318

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	3.9	-	4	4.1	mm
E	package width	3.9	-	4	4.1	mm
A	seated height	-	-	-	0.5	mm
e	nominal pitch	-	-	0.4	-	mm
n ₂	actual quantity of termination	-	-	32	-	A/A



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2. Package outline

HXQFN32: plastic thermal enhanced extremely thin quad flat package; no leads; 32 terminals; body 4 x 4 x 0.5 mm

SOT1318-1

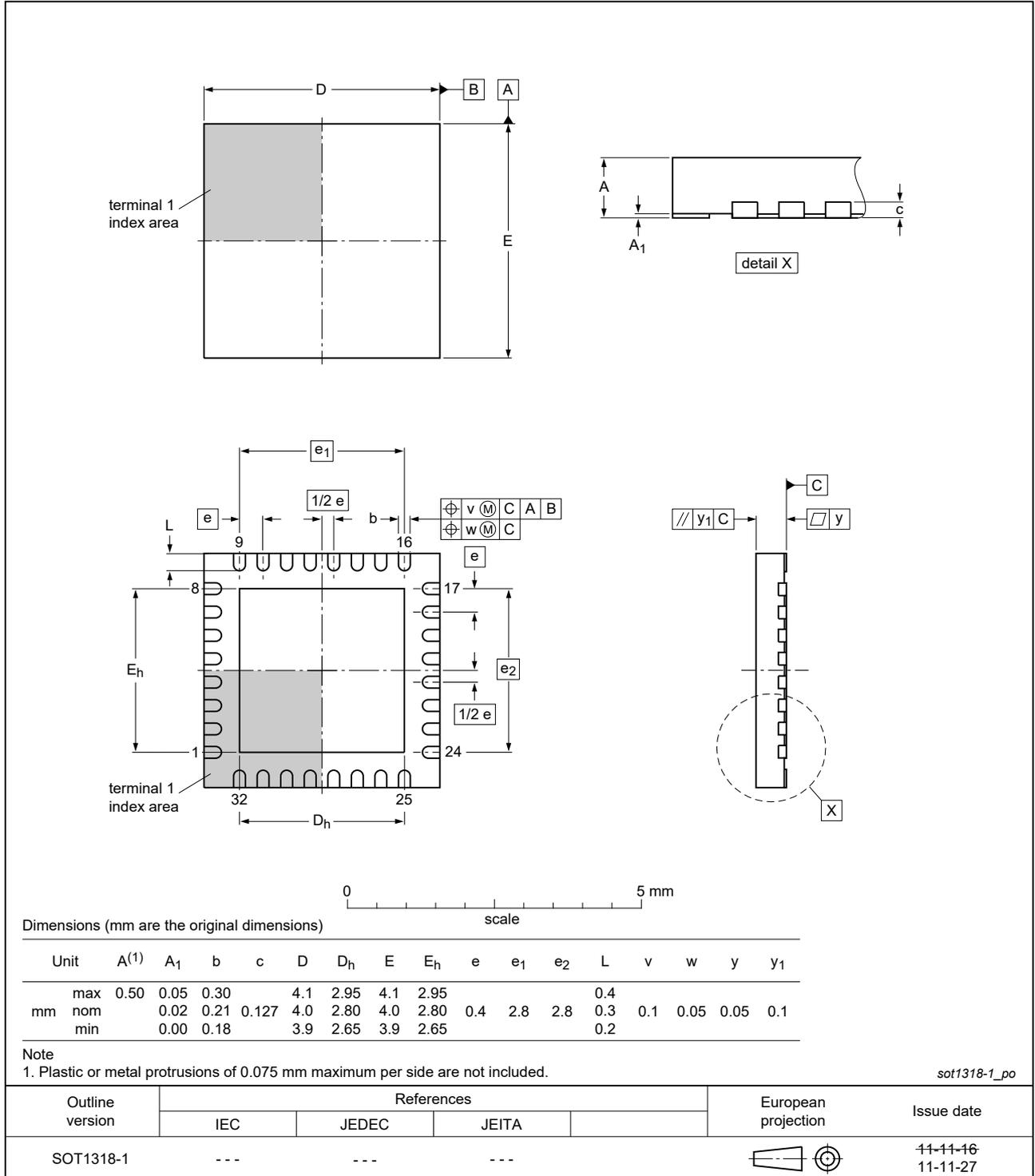


Fig. 1. Package outline HXQFN32 (SOT1318-1)

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3. Legal information

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